

Dynatex DTX-200 by CLT

Scribe and Break

For over 170 years, Corning has applied its unparalleled expertise in glass science, ceramic science, and optical physics. Now, Corning Laser Technologies (CLT) is leveraging 20-plus years of experience in precision laser machining with Dynatex International's 60 years expertise in die singulation.

CLT's unique nanoPerforation technology provides a modification trace through the entire thickness of glass (0.1mm to 2.0mm) in a single pass and allows for subsequent high-quality breaks with the DTX-200. The CLT 400S-WD is a dedicated tool for the nanoPerforation of glass wafers at unparalleled speeds (up to 500mm/s).

Functionality:

- High precision production and R&D tool
- Automatic Mode for simple vision assist/controlled processing
- Interactive/Wizard mode for operator controlled sequencing / processing
- User friendly GUI with touch screen operation for ease of use

Applications:

- Semiconductor devices and optical system with wafer-based glass
- RFICs
- Si-Photonics III-V chips
- Laser Diode Cleaving and Matrix Bar-to-Die separation
- OptoElectronics Devices (PhotoDiodes, Modulators, etc.)
- MEMS and BioMedical devices with sensitive structures/coatings
- LED separation (typically Break Only application)

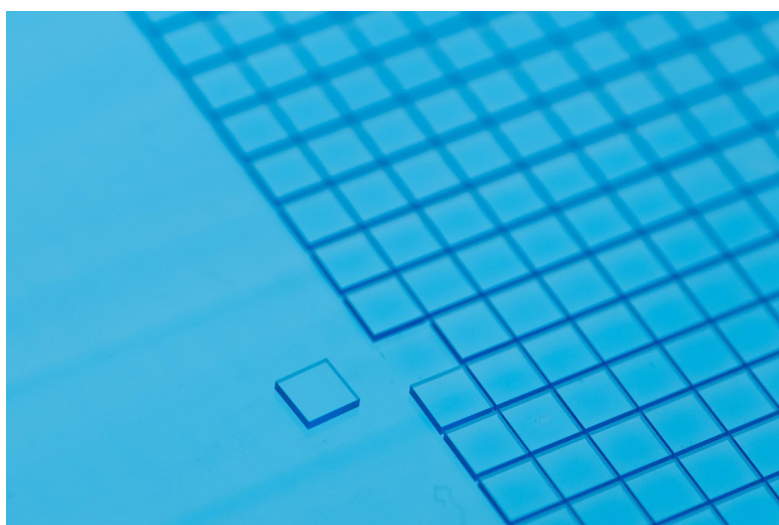


DTX Scribe and Break Features:

- Full Automatic Processing; or Operator Driven Processing
- Up to 200 mm Wafer, and Small Piece Processing
- Integrated Scribe and Break Stages
- Multiple Break Types/Assemblies Available

System Specifications:

Power Required	100/120 VAC 20 amp OR 220/240 VAC 10 amp 50/60 Hz
Operating Temperature	60-80° F (15-27° C), 40-60% relative humidity
Height	1981 mm (78 in)
Width	1477 mm (57 in)
Depth	1270 mm (50 in)
Chuck/Capacity	Up to 200 mm square or round wafer size
Break Time	~0.75 to 1.5 seconds per/break



CORNING
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